

CHIP REMOVER

# T-CHIPEX 1

System for removal of adhesive attached Semiconductor and SMD devices.

It provides a fast and exact positioning of the component to be removed, pre-heating of the whole substrate, focused heating of the defective device and building-up of a shear force, necessary for the separation of the component. Depending on component size, the acting of the force can be static, dynamic or combined static and dynamic.

Revolver head

Top and bottom Heater

Controlled shear force

Easy to use



REWORK

T-CHIPEX 1



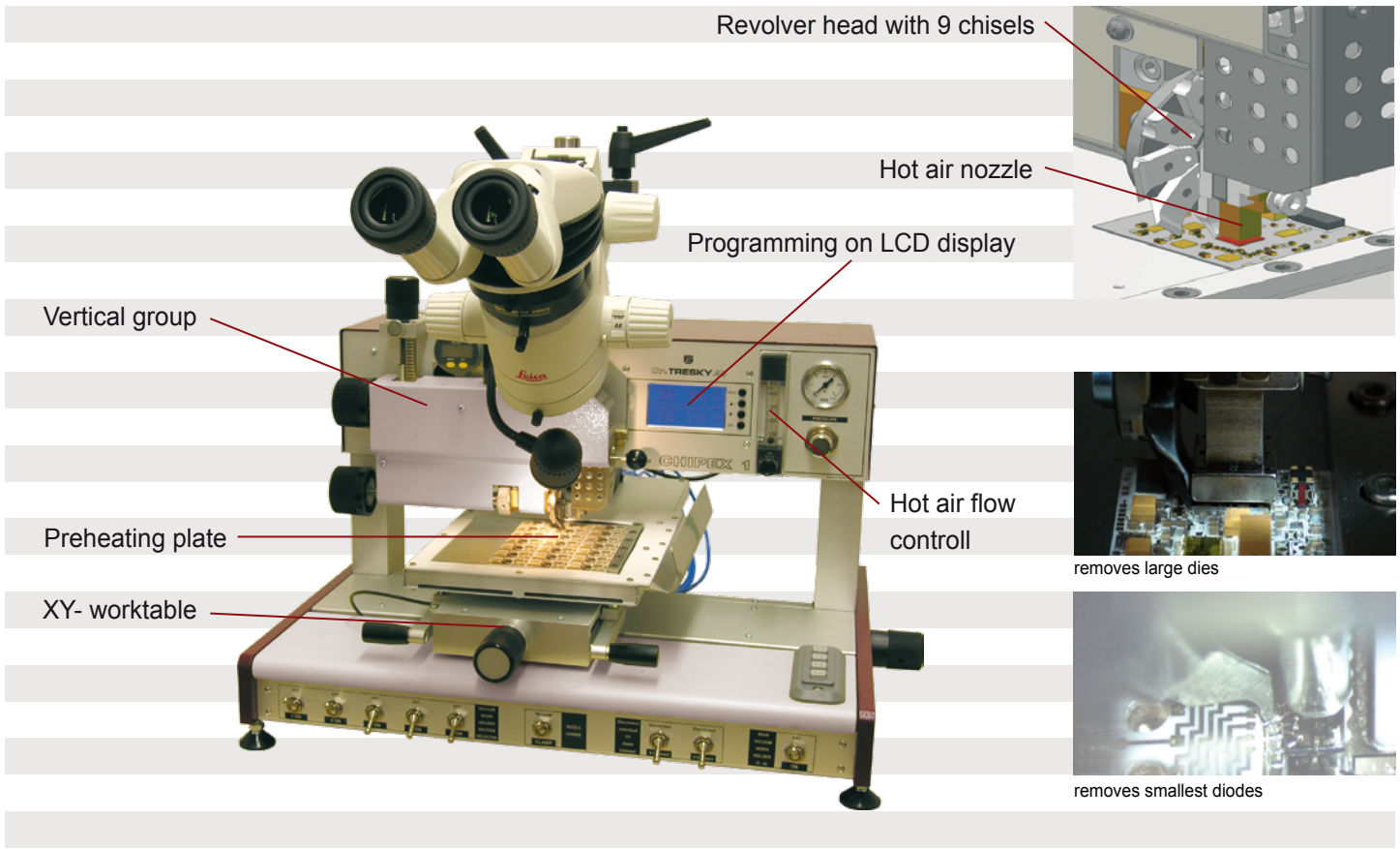
# TRESKY

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**TECHNICAL DATA:**

XY- Movement:	160mm x 160mm
Preheating Plate Size:	150mm x 160mm
Max. Temperature of Preheating Plate:	200°C
Max. Temperature of Hot Gas:	400°C
Z- Movement:	Revolver head with 9 chisels
Number of Chisels:	1mm (smaller custom designed sizes available)
Min. Chisel Size:	12mm (larger custom designed sizes available)
Max. Chisel Size:	400mm x 280mm
Compressed Air:	min. 6 bar
Vacuum:	To hold down Substrate on heating plate
Dimensions:	620mm x 660mm x 530mm
Weight:	30kg
Voltage:	110V / 220V

**REPRESENTED BY:**

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